

Fig. 1

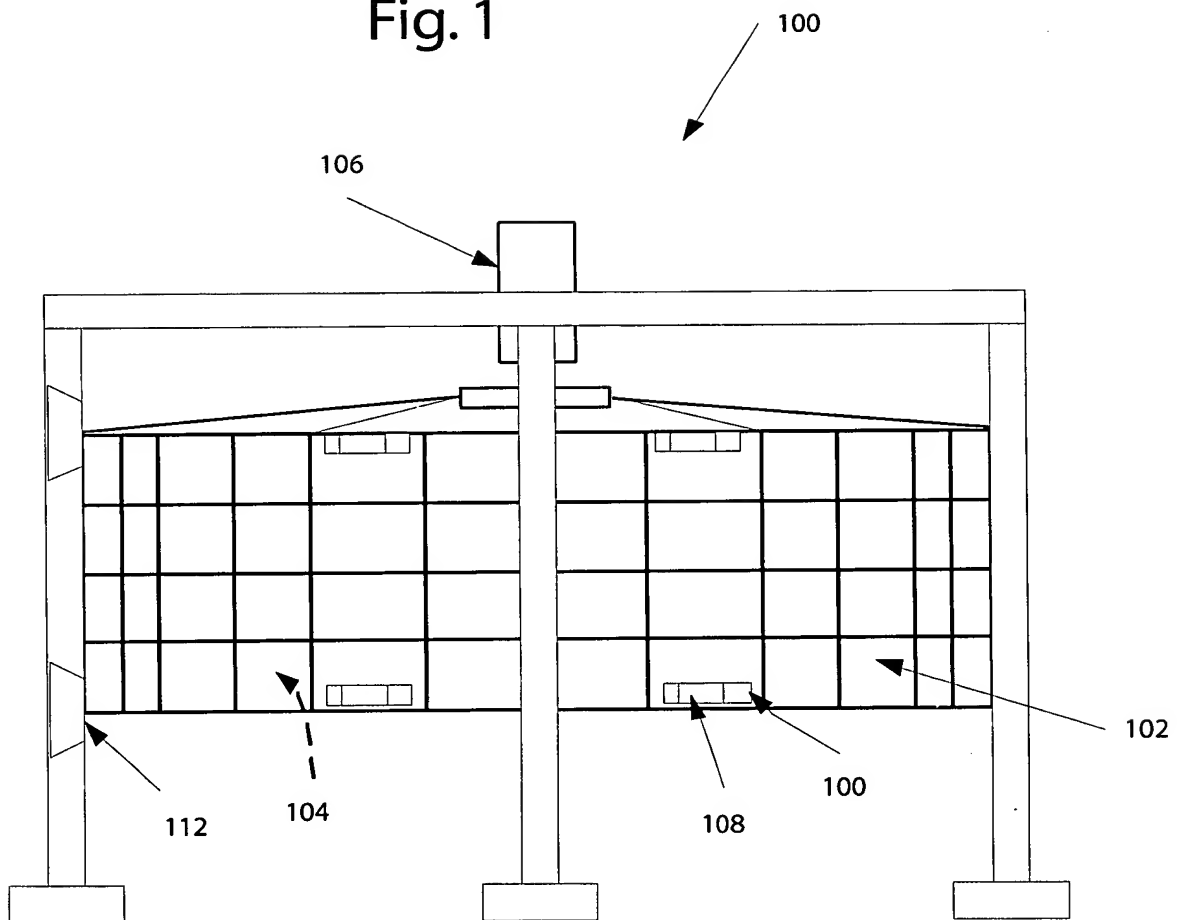


Fig. 2

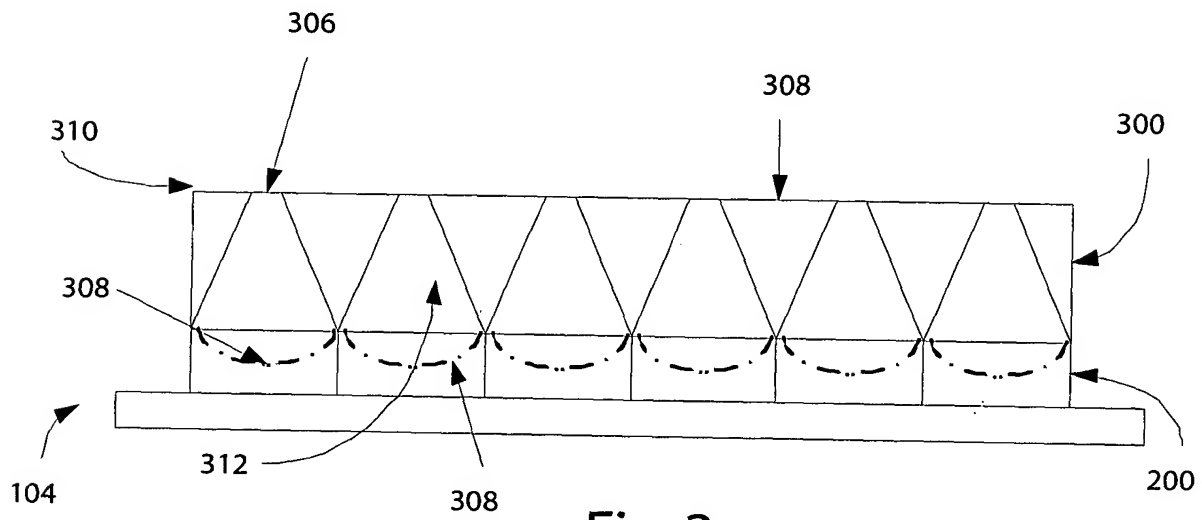
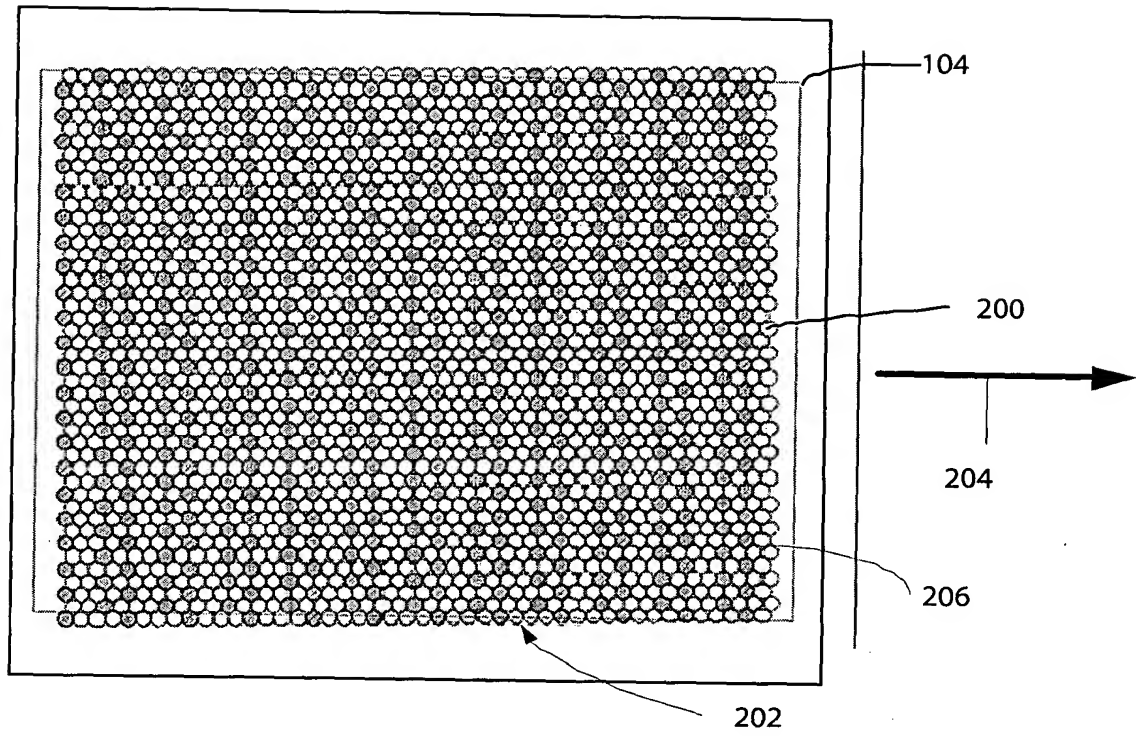


Fig. 3

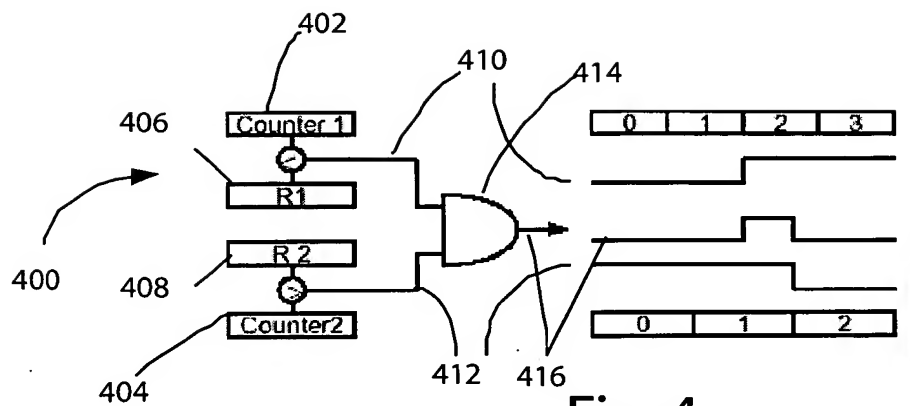


Fig. 4

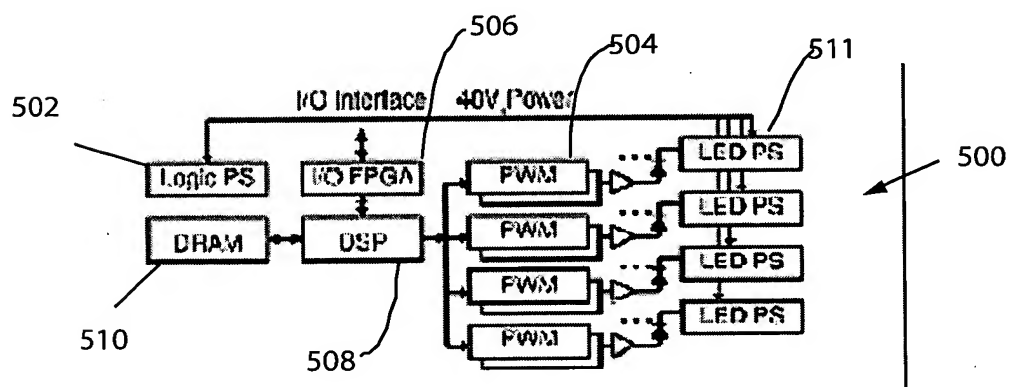
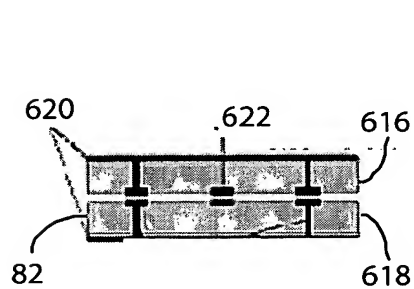


Fig. 5

A cross-sectional view of a multi-layered device assembly. The assembly consists of a base layer (602) supporting a stack of horizontal layers (618, 620). On top of the stack, there are two side components (611, 612) and a central component (600). The side components (611, 612) are connected to the base layer (602) via vertical structures (604, 614). The central component (600) is connected to the base layer (602) via a vertical structure (628). The entire assembly is labeled 106.



The diagram shows a 3dB Hybrid Coupler (623) with an input (622) and an output (626). It includes termination points (R-term) and a reference point (624).

Fig. 6C

Fig. 7

